



SOT788-8

HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.4 mm pitch, 6 mm x 6 mm x 0.85 mm body

27 July 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-06-2020
Manufacturer package code	98ASA01649D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	48	-	



HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.4 mm pitch, 6 mm x 6 mm x 0.85 mm body

2 Package outline

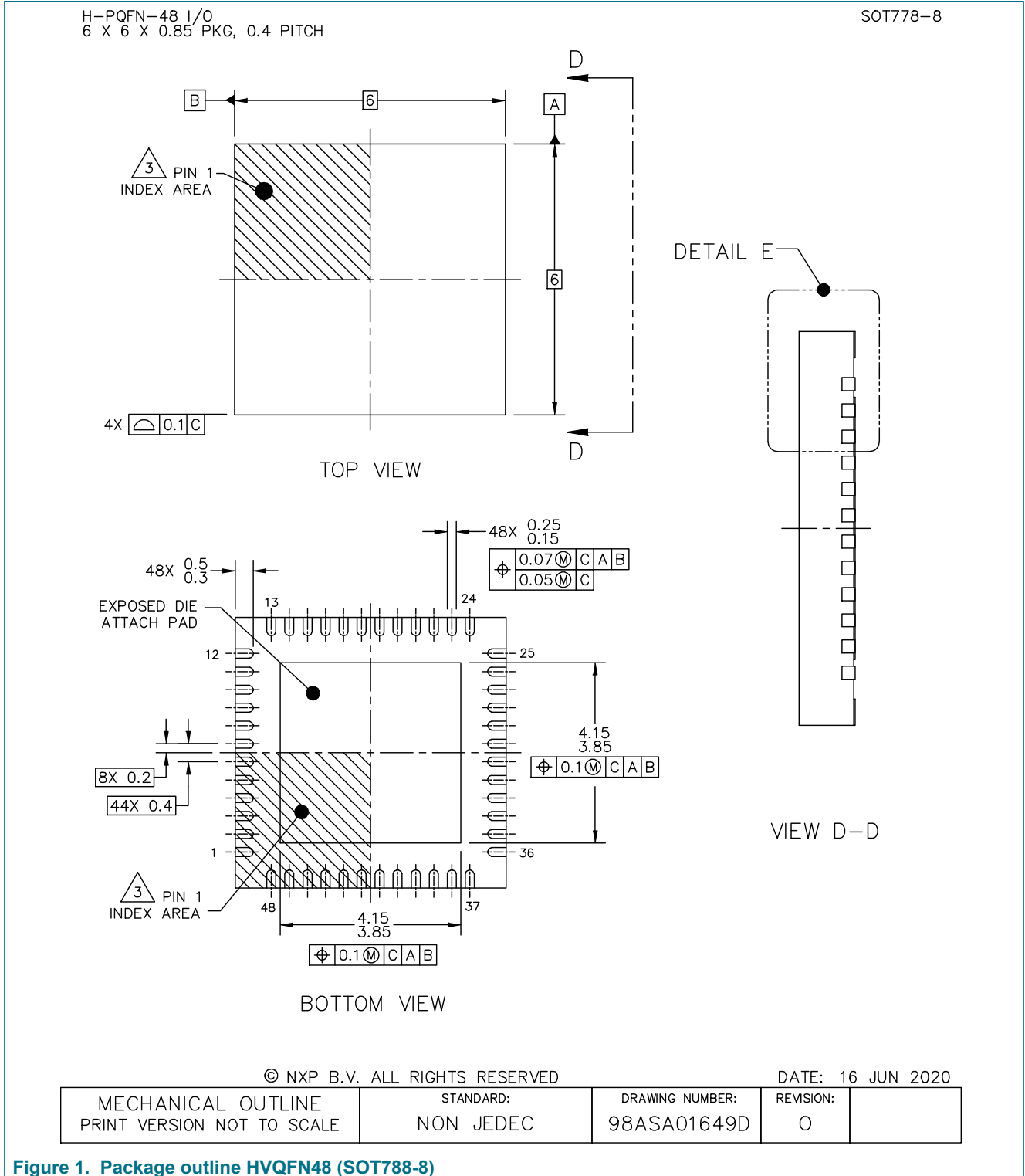
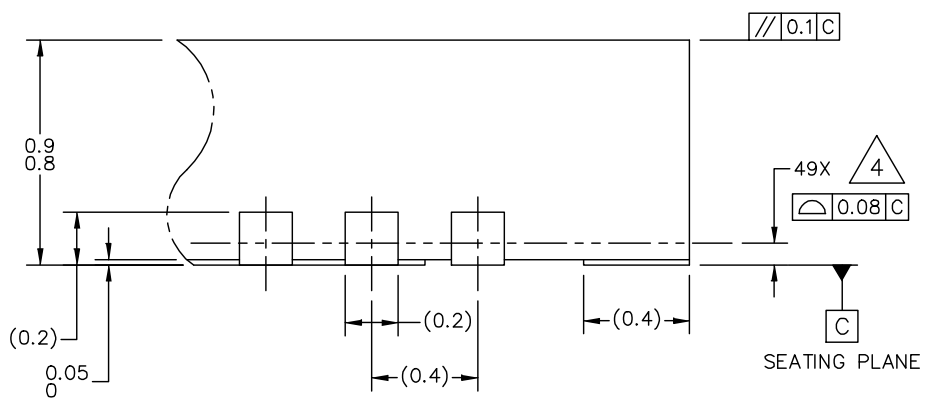


Figure 1. Package outline HVQFN48 (SOT788-8)

HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.4 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-48 I/O
6 X 6 X 0.85 PKG, 0.4 PITCH

SOT778-8



DETAIL E
VIEW ROTATED 90° CW

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Figure 2. Package outline detail HVQFN48 (SOT788-8)

3 Soldering

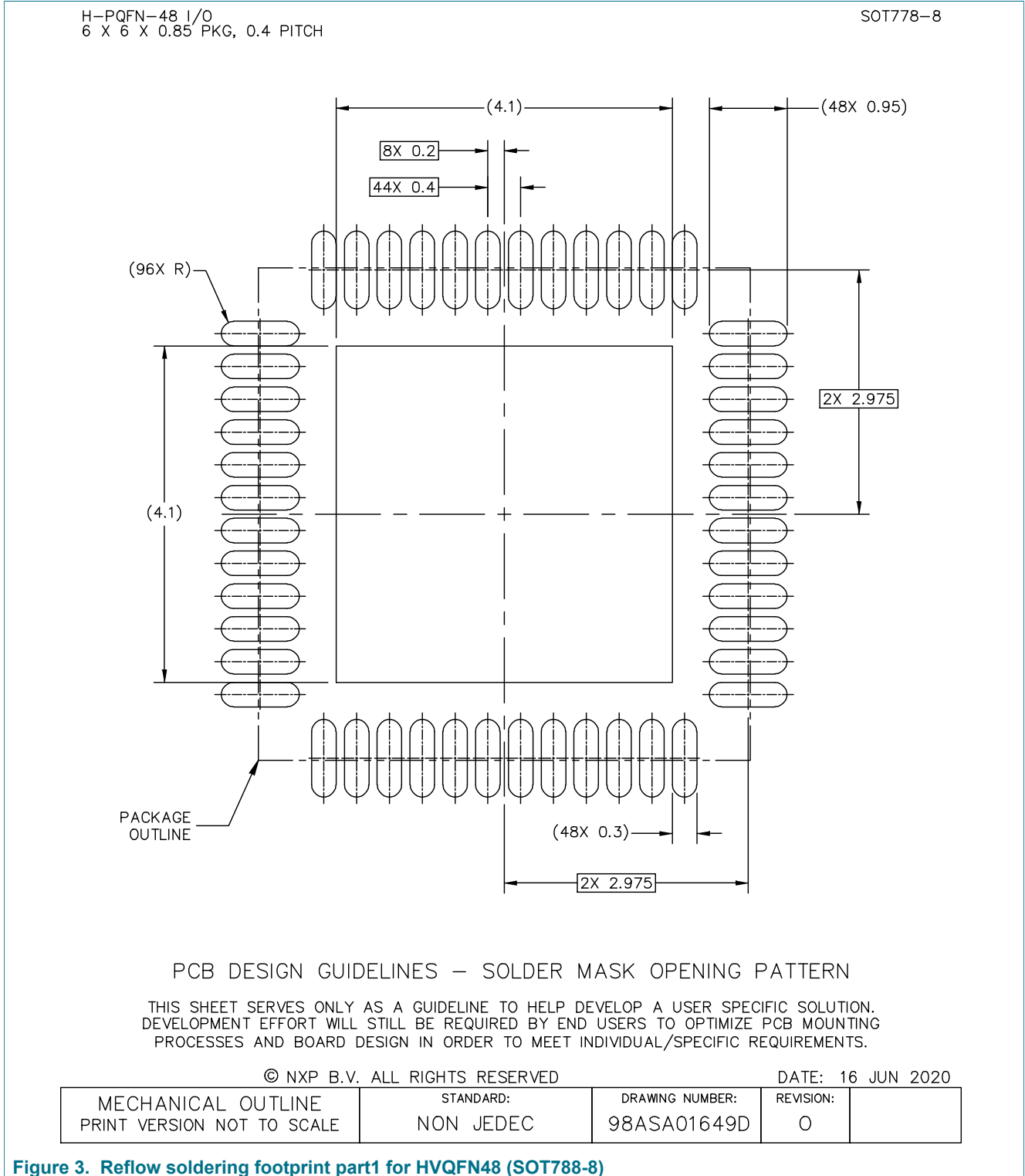
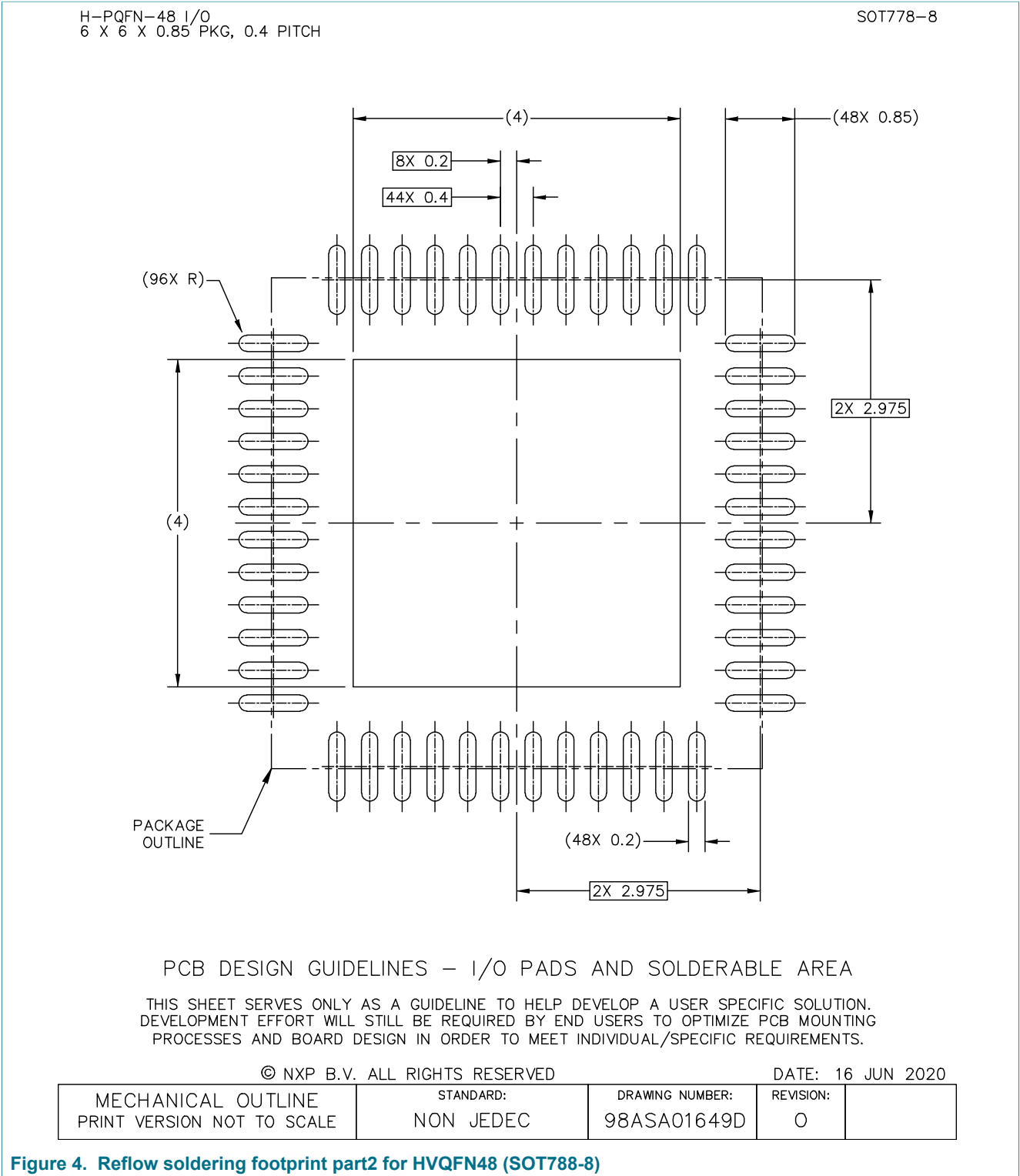


Figure 3. Reflow soldering footprint part1 for HVQFN48 (SOT788-8)

HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.4 mm pitch, 6 mm x 6 mm x 0.85 mm body



HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.4 mm pitch, 6 mm x 6 mm x 0.85 mm body

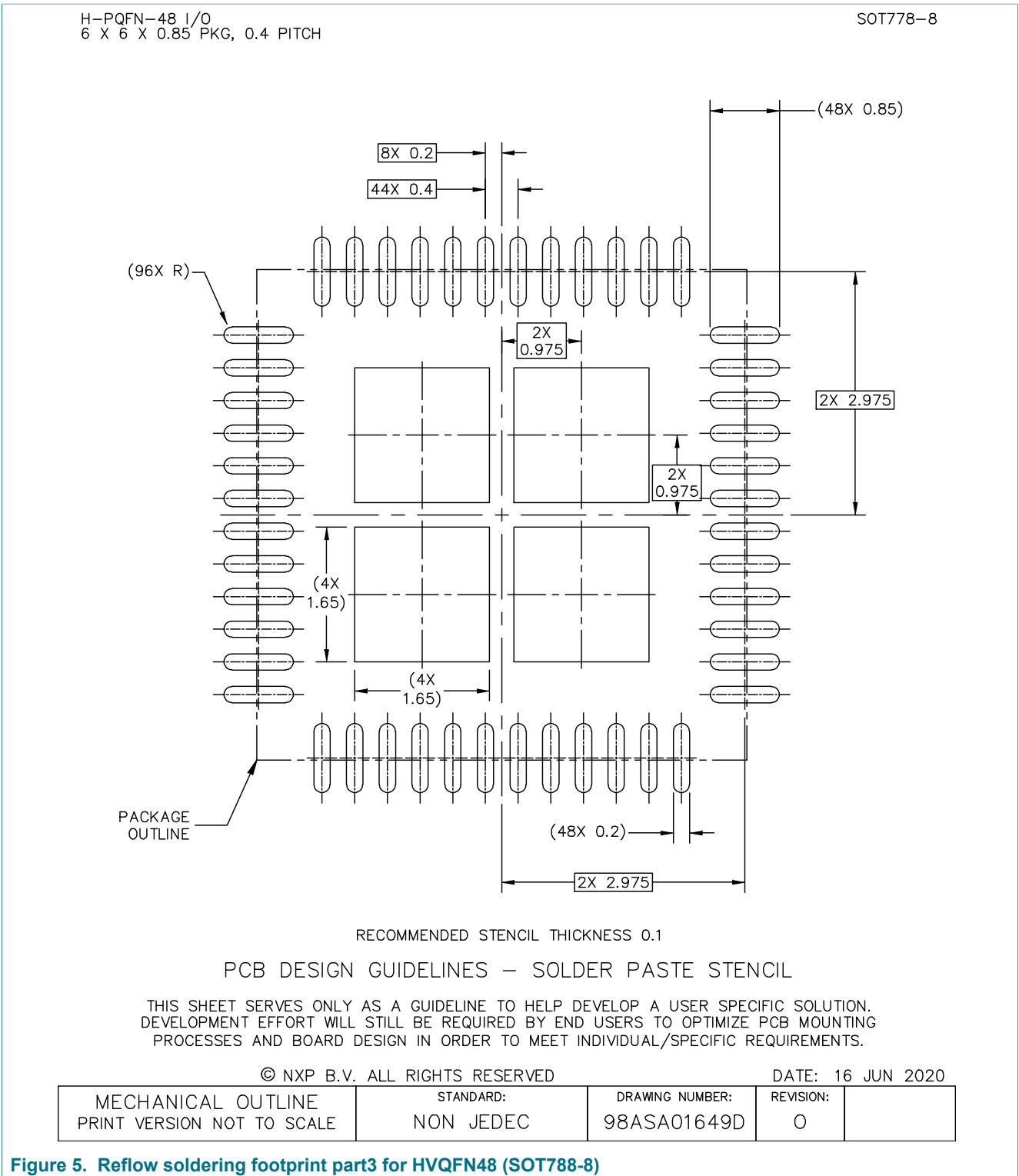


Figure 5. Reflow soldering footprint part3 for HVQFN48 (SOT788-8)

HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.4 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-48 I/O
6 X 6 X 0.85 PKG, 0.4 PITCH

SOT778-8

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN48 (SOT788-8)

HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.4 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-48 I/O
6 X 6 X 0.85 PKG, 0.4 PITCH

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Figure 7. Package outline note HVQFN48 (SOT788-8)

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